5-Bit Magnitude Comparator

The MC10H166 is a 5-Bit Magnitude Comparator and is a functional/pinout duplication of the standard MECL 10K part with 100% improvement in propagation delay and no increase in power-supply current.

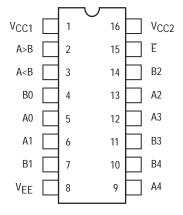
The MC10H166 is a high–speed expandable 5–bit comparator for comparing the magnitude of two binary words. Two outputs are provided: A < B and A > B. The A = B function can be obtained by wire–ORing these outputs (a low level indicates A = B) or by wire–NORing the outputs (a high level indicates A = B). A high level on the enable function forces both outputs low.

- Propagation Delay, Data-to-Output, 2.0 ns Typical
- Power Dissipation 440 mW Typical
- Improved Noise Margin 150 mV (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K-Compatible

TRUTH TABLE

	Inputs	Outputs		
Ē	Α	В	A < B	A > B
Н	Х	Х	L	L
L	WORD A =	= WORD B	L	L
L	WORD A	> WORD B	L	Н
L	WORD A	< WORD B	Н	L

DIP PIN ASSIGNMENT



Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).

1



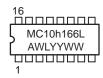
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http://onsemi.com

MARKING DIAGRAMS

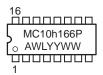


CDIP-16 L SUFFIX CASE 620





PDIP-16 P SUFFIX CASE 648





PLCC-20 FN SUFFIX CASE 775



A = Assembly Location

WL = Wafer Lot YY = Year

WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping	
MC10h166L	CDIP-16	25 Units/Rail	
MC10h166P	PDIP-16	25 Units/Rail	
MC10h166FN	PLCC-20	46 Units/Rail	

MAXIMUM RATINGS

Symbol	Characteristic	Rating	Unit	
VEE	Power Supply (V _{CC} = 0)	-8.0 to 0	Vdc	
VI	Input Voltage (V _{CC} = 0)	0 to VEE	Vdc	
l _{out}	Output Current – Continuous – Surge	50 100	mA	
TA	Operating Temperature Range	0 to +75	°C	
T _{stg}	Storage Temperature Range – Plastic – Ceramic	−55 to +150 −55 to +165	ိ	

ELECTRICAL CHARACTERISTICS ($V_{\mbox{EE}} = -5.2 \mbox{ V } \pm 5\%$) (See Note 1.)

		0	0	2	5°	7	′5°	
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
ΙE	Power Supply Current	_	117	1	106	-	117	mA
linH	Input Current High	_	350	-	220	-	220	μΑ
l _{inL}	Input Current Low	0.5	_	0.5	-	0.3	_	μΑ
Voн	High Output Voltage	-1.02	-0.84	-0.98	-0.81	-0.92	-0.735	Vdc
VOL	Low Output Voltage	-1.95	-1.63	-1.95	-1.63	-1.95	-1.60	Vdc
VIH	High Input Voltage	-1.17	-0.84	-1.13	-0.81	-1.07	-0.735	Vdc
VIL	Low Input Voltage	-1.95	-1.48	-1.95	-1.48	-1.95	-1.45	Vdc

AC PARAMETERS

^t pd	Propagation Delay Data-to-Output Enable-to-Output	1.1 0.6	3.5 1.7	1.1 0.7	3.7 1.7	1.2 0.7	4.1 1.8	ns
t _r	Rise Time	0.6	1.5	0.6	1.6	0.6	1.7	ns
tf	Fall Time	0.6	1.5	0.6	1.6	0.6	1.7	ns

^{1.} Each MECL 10H series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained. Outputs are terminated through a 50–ohm resistor to –2.0 volts.

LOGIC DIAGRAM

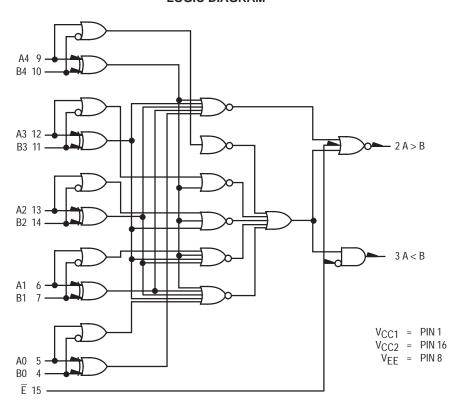
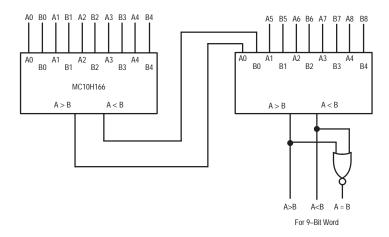


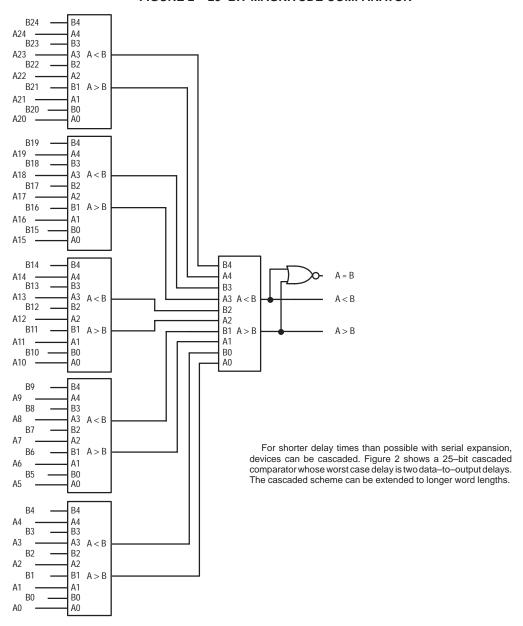
FIGURE 1 - 9-BIT MAGNITUDE COMPARATOR



For longer word lengths, the MC10H166 can be serially expanded or cascaded. Figure 1 shows two devices in a serial expansion for a 9-bit word length. The A>B and A<B outputs are fed to the A0 and B0 inputs respectively

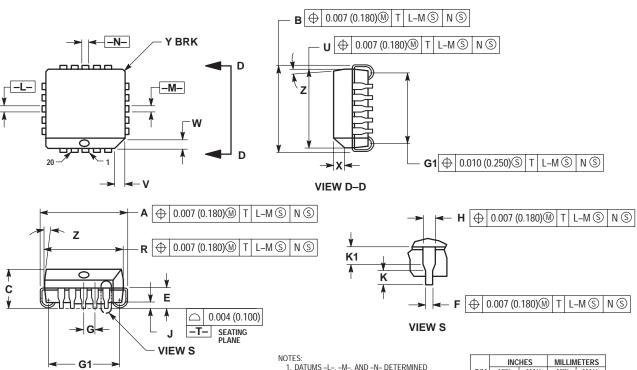
of the next device. The connection for an A=B output is also shown. The worst case delay time of serial expansion is equal to the number of comparators times the data—to—output delay.

FIGURE 2 – 25-BIT MAGNITUDE COMPARATOR



PACKAGE DIMENSIONS

PLCC-20 **FN SUFFIX** PLASTIC PLCC PACKAGE CASE 775-02 **ISSUE C**



- WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
- 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD.
- FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

 4. DIMENSIONING AND TOLERANCING PER ANSI
- 4. DIMENSIONING AND TOLERANCING FER ANSI Y14.5M, 1982. 5. CONTROLLING DIMENSION: INCH. 6. THE PACKAGE TOP MAY BE SMALLER THAN THE

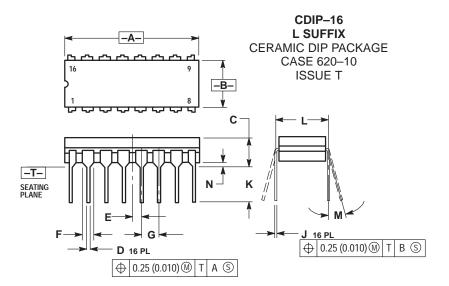
⊕ 0.010 (0.250)⑤ T L-M ⑤ N ⑤

- PACKAGE BOTTOM BY UP TO 0.012 (0.300).
 DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP
- INCLUDING ANY MISMAICH BE I WEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.

 7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Ε	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
Х	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2°	10°	2°	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

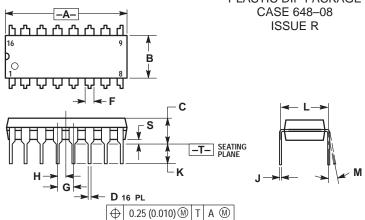
PACKAGE DIMENSIONS



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.020	0.39	0.50	
E	0.050) BSC	1.27 BSC		
F	0.055	0.065	1.40	1.65	
G	0.100	BSC	2.54 BSC		
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300 BSC		7.62 BSC		
M	0°	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	

PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10 °	0 °	10 °	
S	0.020	0.040	0.51	1.01	

Notes

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